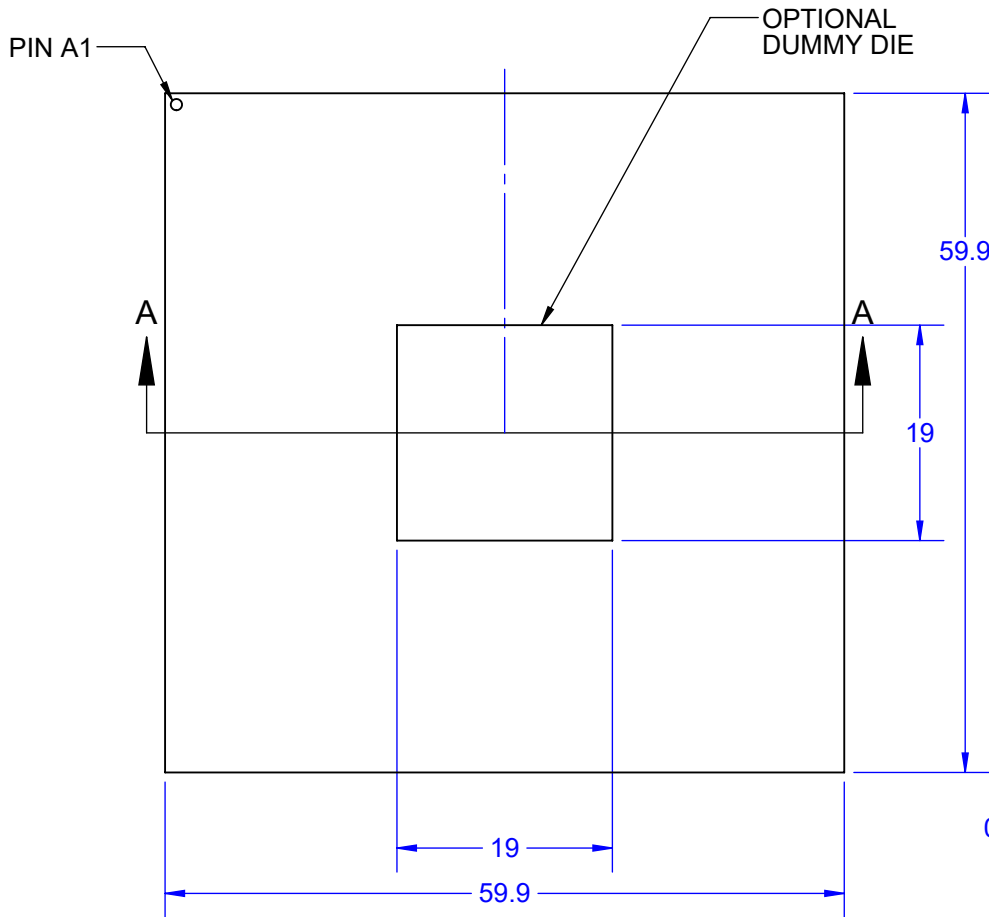
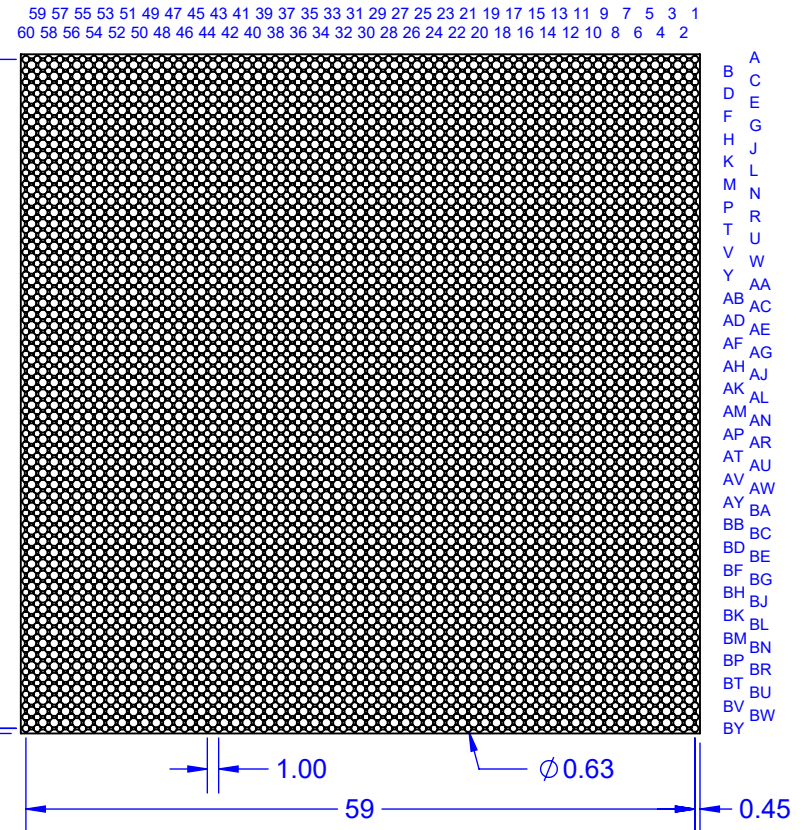


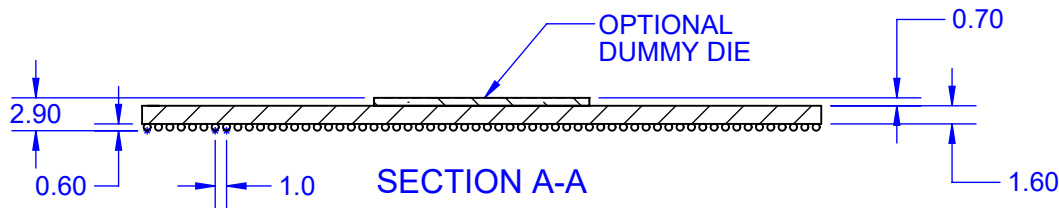
TOP VIEW



BALL VIEW



- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.635mm [25MIL].
 - 4) SOLDER MASK DEFINED PAD OPENING: 0.508mm [20 MIL].
 - 5) PAD Cu DIAMETER: 0.685mm [27 MIL].
 - 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT).
 - 7) DUMMY DIE IS OPTIONAL.
 - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.



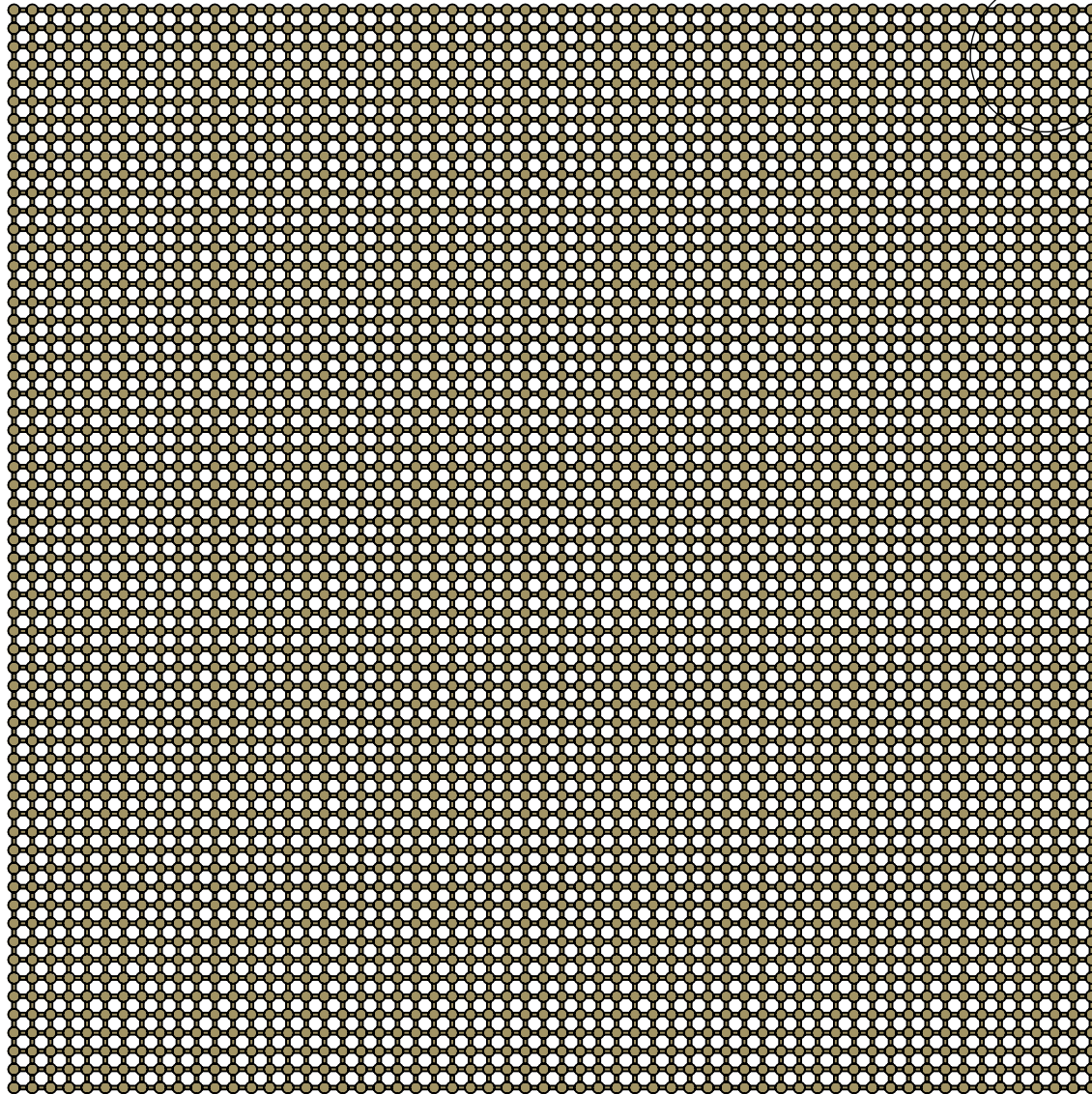
PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
LBGA3600T1.0C-BUS	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA3600T1.0C-BUS-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA3600T1.0-BUS	Sn63/Pb37	NO	NO	NO
LBGA3600T1.0-BUS-D	Sn63/Pb37	NO	NO	YES

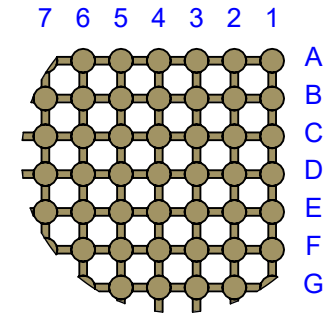
APPROVALS	DATE				
DRAWN T.Au	08/19/15				
ENG M. Hart	08/19/15	TITLE LBGA3600T1.0-BUS ALL PADS SHORTED			
MFG		SCALE 3:2	SIZE A	DRAWING NO. 546011	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 3
CUST					
REVISED					

BALL VIEW

59 57 55 53 51 49 47 45 43 41 39 37 35 33 31 29 27 25 23 21 19 17 15 13 11 9 7 5 3 1
 60 58 56 54 52 50 48 46 44 42 40 38 36 34 32 30 28 26 24 22 20 18 16 14 12 10 8 6 4 2



B
 A
 B
 C
 D
 E
 F
 G
 H
 J
 K
 L
 M
 N
 P
 R
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 U
 V
 W
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 AA
 AB
 AC
 AD
 AE
 AF
 AG
 AH
 AJ
 AK
 AL
 AM
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 AP
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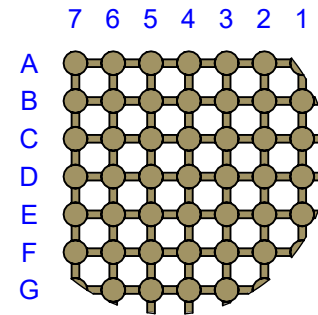
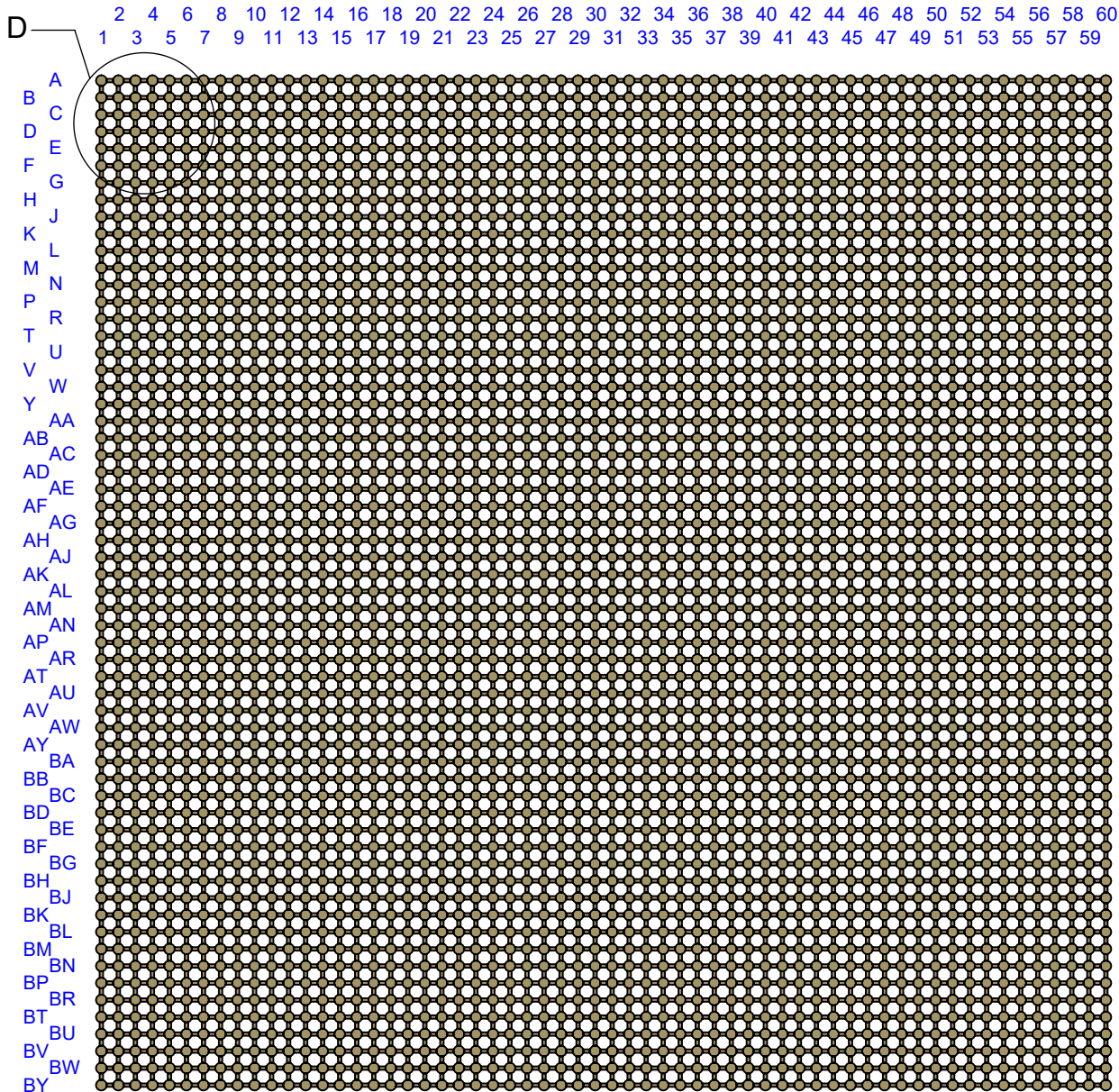
DETAIL B
 SCALE 5 : 1
 ALL PADS
 CONNECTED

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.685mm [27 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.204mm [8 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.508mm [20 MIL].

TopLine®			
TITLE		LBGA3600T1.0-BUS ALL PADS SHORTED	
SCALE	SIZE	DRAWING NO.	REV
1:1	A	546011	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

BOTTOM SIDE (TOP X-RAY VIEW)



DETAIL D
SCALE 5 : 1
ALL PADS
CONNECTED

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.685mm [27 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.204mm [8 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.508mm [20 MIL].

TopLine®			
TITLE		LBGA3600T1.0-BUS ALL PADS SHORTED	
SCALE	SIZE	DRAWING NO.	REV
1:1	A	546011	A
DO NOT SCALE DRAWING			SHEET 3 OF 3